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Interested committees:

Title: BS EN IEC 62047-52 Semiconductor devices - Micro-electromechanical devices

Part 52: Biaxial tensile testing method for stretchable MEMS

Please notify the secretary if you are aware of any keywords that might assist in classifying or identifying the standard or if the content of this standard

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- ii) affects other national standard(s)
- iii) requires additional national guidance or information

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Introduction

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

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UK Vote

Please indicate whether you consider the UK should submit a negative (with supporting technical reasons) or positive vote on this draft. Please indicate if you are aware of any reason why this draft standard should not be published as a British Standard.

Submission of Comments

- **Annotated drafts are not acceptable and will be rejected.**
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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx
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1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex (e.g. 3.1)	Paragraph/Figure/ Table/Note	Type of comment	Commend (justification for change) by the MB	Proposed change by the MB	Secretariat observations on each comment submitted
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	



47F/483/CD

COMMITTEE DRAFT (CD)

PROJECT NUMBER: IEC 62047-52 ED1	
DATE OF CIRCULATION: 2024-09-13	CLOSING DATE FOR COMMENTS: 2024-11-08
SUPERSEDES DOCUMENTS: 47F/457/NP, 47F/467A/RVN	

IEC SC 47F : MICRO-ELECTROMECHANICAL SYSTEMS	
SECRETARIAT: Japan	SECRETARY: Mr Takashi Mihara
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:	

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Recipients of this document are invited to submit, with their comments, notification of any relevant patent rights of which they are aware and to provide supporting documentation.

Recipients of this document are invited to submit, with their comments, notification of any local regulations or technical reasons that may exist and should be considered should this proposal proceed, recognizing that failure to address such requirements could result in the need for new or existing "In Some Countries" clauses. (SEE [AC/22/2007](#) OR [NEW GUIDANCE DOC](#)).

TITLE:

Semiconductor Devices - Micro-electromechanical Devices - Part 52: Biaxial tensile testing method for stretchable MEMS

NOTE FROM TC/SC OFFICERS:

This draft of CD was made based on the discussion at WG2 held on 24-05-23 in Jeju Island and the observation of 47F/467A/RVN.

Secretary of SC47F would like to request the 8-weeks commenting period to get the comment compilation of this CD voting before the next SC47F/WG2 on 24-11-23 in London.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –****Part 52: Biaxial tensile testing method for stretchable MEMS****FOREWORD**

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International Standard IEC 62047-52 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
XX/XX/FDIS	XX/XX/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.